



Material Content Data Sheet



Sales Product Name		BAS 16S H6327		Issued		19. July 2018		
MA#		MA000845486						
Package		PG-SOT363-6-3		Weight*		6.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		24	
	noble metal	gold	7440-57-5	0.015	0.23		2342	
	inorganic material	silicon	7440-21-3	0.052	0.80	1.03	8001	10366
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		96	
	non noble metal	titanium	7440-32-6	0.003	0.05		480	
	non noble metal	chromium	7440-47-3	0.009	0.14		1440	
	non noble metal	copper	7440-50-8	3.093	47.80	48.00	477970	479987
wire	non noble metal	copper	7440-50-8	0.015	0.24	0.24	2384	2384
encapsulation	organic material	carbon black	1333-86-4	0.030	0.46		4641	
	plastics	epoxy resin	-	0.646	9.98		99782	
	inorganic material	silicondioxide	60676-86-0	2.327	35.97	46.41	359678	464100
leadfinish	non noble metal	tin	7440-31-5	0.213	3.30	3.30	32954	32954
plating	noble metal	silver	7440-22-4	0.066	1.02	1.02	10208	10208
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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